

/ Descriptions

玻璃钝化整流桥，反向电压：50~1000V，正向电流：35 A，GBJ 封装。

Glass Passivated Bridge Rectifiers, Reverse Voltage:50~1000V,Forward Current:35A,GBJ package.

/ Features

优化 PCB 板选择，塑料模具外壳，塑料的 UL 易燃性等级为 94V-0。无卤产品。

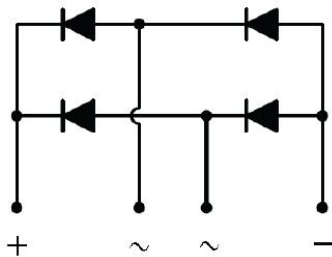
Ideal for printed circuit board, Case material molded plastic, The plastic material has U/L flammability classification 94V-0. Halogen free product.

/ Applications

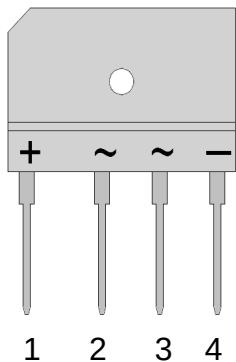
一般用途。

General purpose.

/ Equivalent Circuit



/ Pinning



PIN1 : DC+ PIN2 : AC PIN 3 : AC PIN 4 : DC-

/ h_{FE} Classifications & Marking

见印章说明。 See Marking Instructions

/ Absolute Maximum Ratings(Ta=25)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		GBJ 35005G	GBJ 3501G	GBJ 3502G	GBJ 3504G	GBJ 3506G	GBJ 3508G	GBJ 3510G	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current (with heatsink Note 2)	$I_{F(AV)}$	35							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I_{FSM}	350							A
I^2t Rating for Fusing (t<8.3ms)	I^2t	508							A ² s
Typical Junction Capacitance Per Element (Note1)	CJ	114							pF
Typical Thermal Resistance (Note2)	$R_{\theta Jc}$	1.0							°C/W
Operating Temperature Range	T_j	-55 to +150							°C
Storage Temperature Range	T_{stg}	-55 to +150							°C

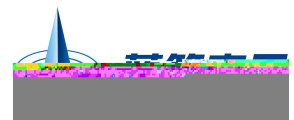
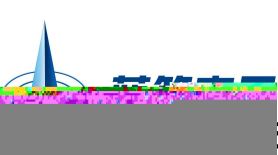
NOTE:

1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2.Device mounted on 150mm*150mm*1.6mm Cu Plate Heatsink.

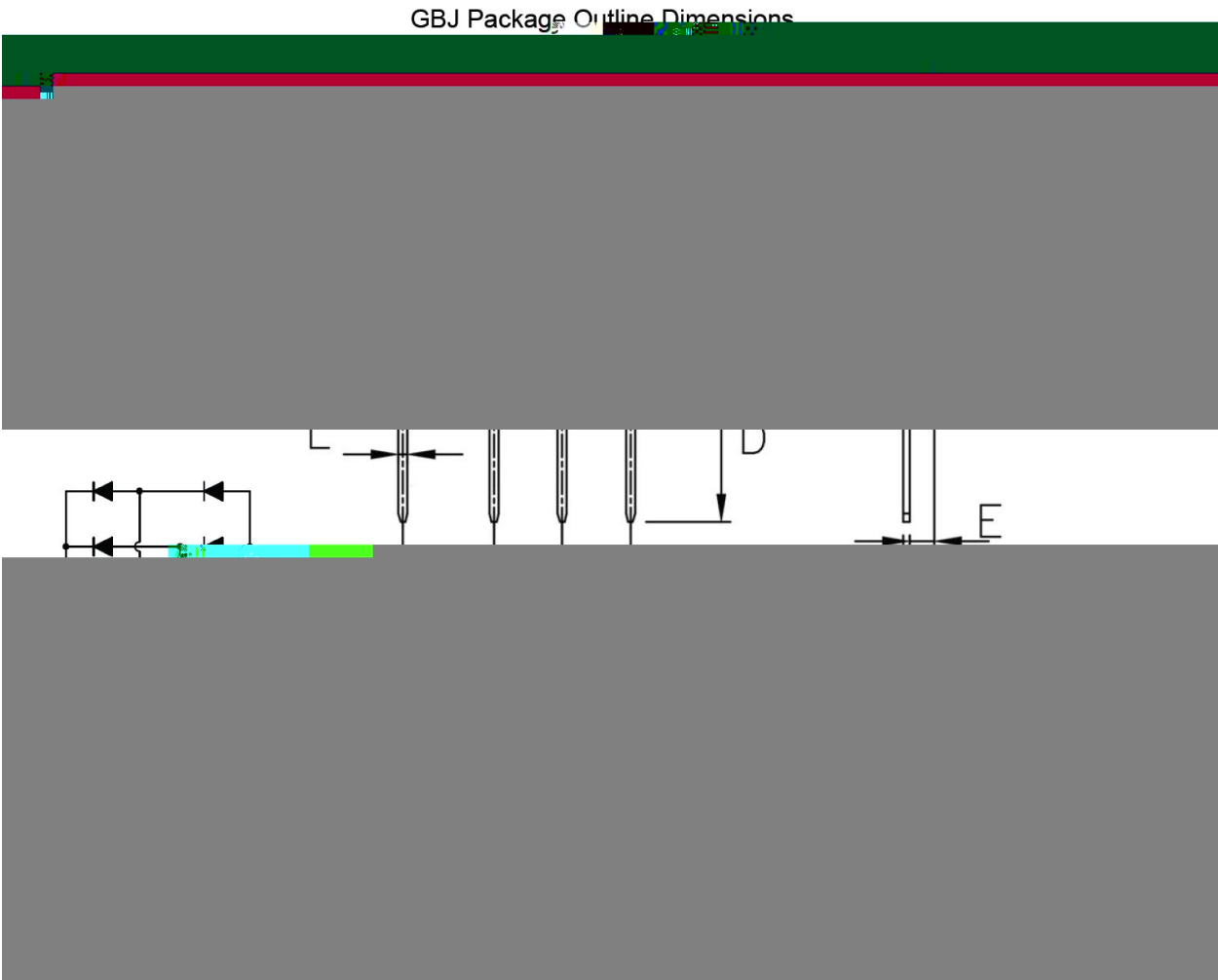
/ Electrical Characteristics(Ta=25)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Maximum Forward Voltage	V_F	$I_F=17.5A$	1.0	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25$	5.0	μA
		$T_a=125$	500	

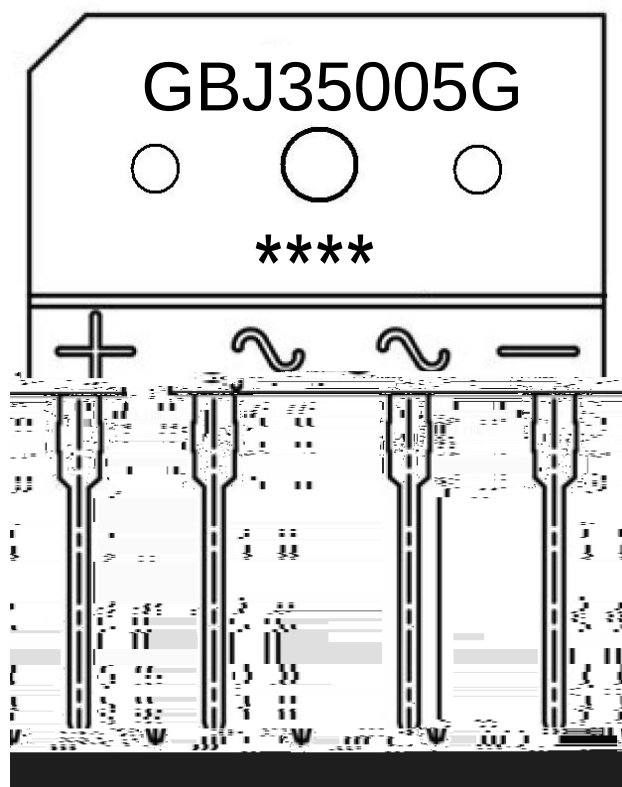


/ Electrical Characteristic

/ Package Dimensions



/ Marking Instructions



说明：

GBJ35005G： 为产品型号

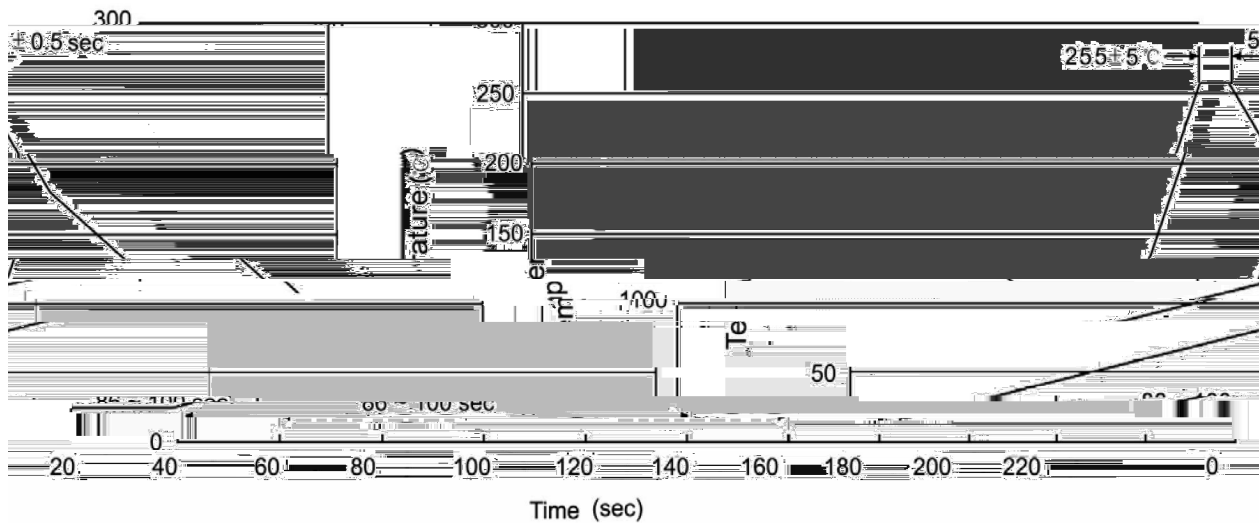
****： 为生产批号代码，随生产批号变化

Note:

GBJ35005G: Product Type.

****: Lot No. Code, code change with Lot No

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5℃ Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag 袋	Inner Box 盒	Outer Box 箱
GBJ	-	-						

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube 套管	Inner Box 盒	Outer Box 箱